

ON Semiconductor®

FQP27P06

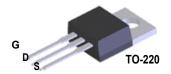
P-Channel QFET $^{\circledR}$ MOSFET - 60 V, - 27 A, 70 m Ω

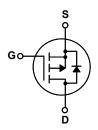
Description

This P-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- - 27 A, 60 V, $R_{DS(on)}$ = 70 m Ω (Max.) @ V_{GS} = 10 V, I_D = 13.5 A
- Low Gate Charge (Typ. 33 nC)
- Low Crss (Typ. 120 pF)
- · 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter			FQP27P06	Unit
V _{DSS}	Drain-Source Vo	oltage		-60	V
I _D	Drain Current	- Continuous (T _C = 25°C)		-27	Α
		- Continuous (T _C = 10	- Continuous (T _C = 100°C)		Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	-108	Α
V_{GSS}	Gate-Source Voltage			± 25	V
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	560	mJ
I _{AR}	Avalanche Current		(Note 1)	-27	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	-7.0	V/ns
P _D	Power Dissipation (T _C = 25°C)			120	W
	- Derate above 25°C			0.8	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQP27P06	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.25	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-0.06		V/°C
I _{DSS}	7 0 1 1/1 5 1 0 1	V _{DS} = -60 V, V _{GS} = 0 V			-1	μА
	Zero Gate Voltage Drain Current	V _{DS} = -48 V, T _C = 150°C			-10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse V _{GS} = 25 V, V _{DS} = 0 V				100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = -250 \mu A$		-2.0		-4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{Ce} = -10 \text{ V. In} = -13.5 \text{ A}$		0.055	0.07	Ω
9 _{FS}	Forward Transconductance	Transconductance $V_{DS} = -30 \text{ V}, I_D = -13.5 \text{ A}$		12.4		S
	ic Characteristics		T	T		T
C _{iss}	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$		1100	1400	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		510	660	pF
C _{rss}	Reverse Transfer Capacitance	Reverse Transfer Capacitance		120	155	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time $V_{DD} = -30 \text{ V, } I_D = -13.5 \text{ A},$			18	45	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		185	380	ns
t _{d(off)}	Turn-Off Delay Time	1.6 2012		30	70	ns
t _f	Turn-Off Fall Time	(Note 4)		90	190	ns
Qg	Total Gate Charge	V _{DS} = -48 V, I _D = -27 A,		33	43	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		6.8	-	nC
Q _{gd}	Gate-Drain Charge	(Note 4)		18	-	nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Did			-27	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode F			-108	Α	
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -27 A			-4.0	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V, I}_{S} = -27 \text{ A},$			105	-	ns
Q _{rr}	Reverse Recovery Charge dl _F / dt = 100 A/μs			0.41	-	μС

Notes:
1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 0.9mH, I_{AS} = -27A, V_{DD} = -25V, R_G = 25 Ω , Starting T_J = 25°C
3. I_{SD} \leq -27A, di/dt \leq 300A/µs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C
4. Essentially independent of operating temperature

Typical Characteristics

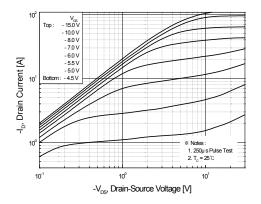


Figure 1. On-Region Characteristics

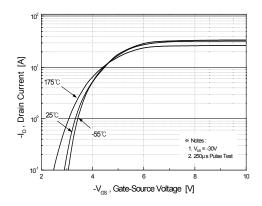


Figure 2. Transfer Characteristics

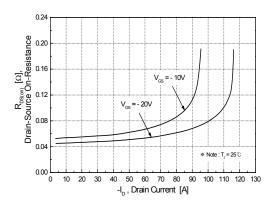


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

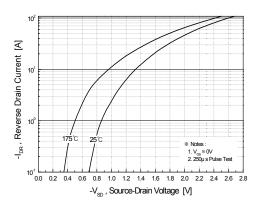


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

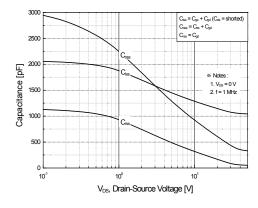


Figure 5. Capacitance Characteristics

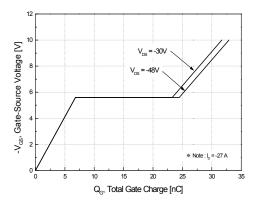
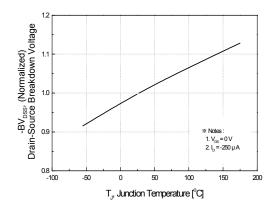


Figure 6. Gate Charge Characteristics

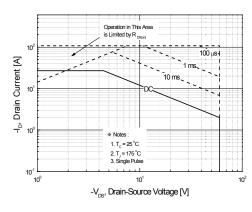
Typical Characteristics (Continued)



25 (Notes: 1.7 (No

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



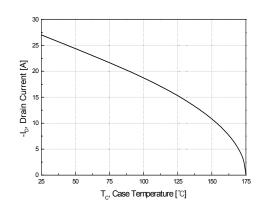


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

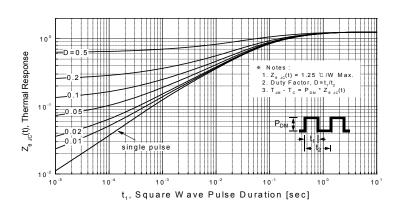
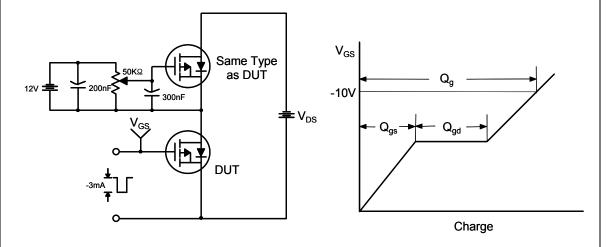
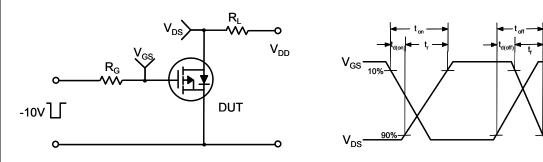


Figure 11. Transient Thermal Response Curve

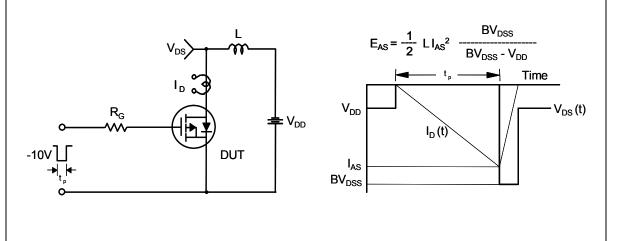
Gate Charge Test Circuit & Waveform



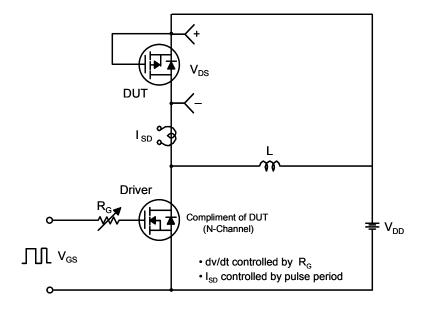
Resistive Switching Test Circuit & Waveforms

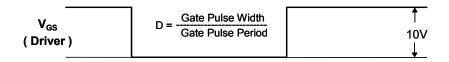


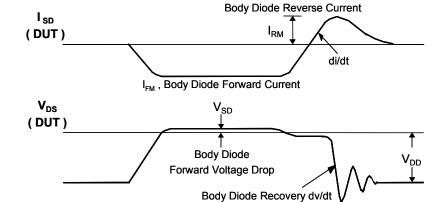
Unclamped Inductive Switching Test Circuit & Waveforms

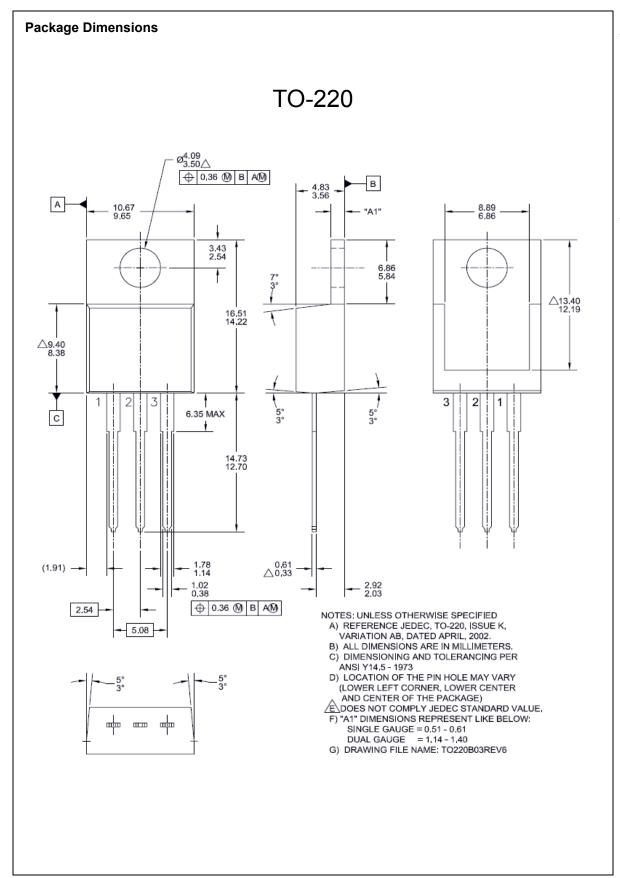


Peak Diode Recovery dv/dt Test Circuit & Waveforms









ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative